

# MECHANICAL CASE OUTLINE

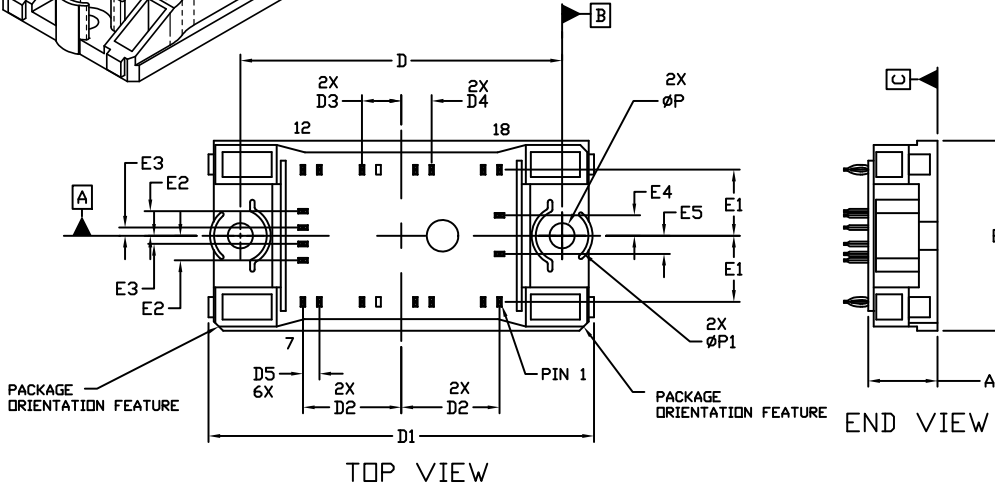
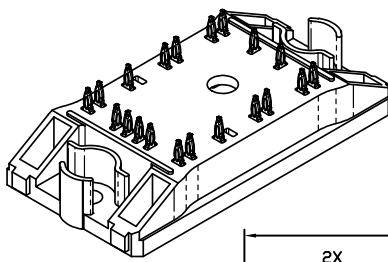
## PACKAGE DIMENSIONS

ON Semiconductor®

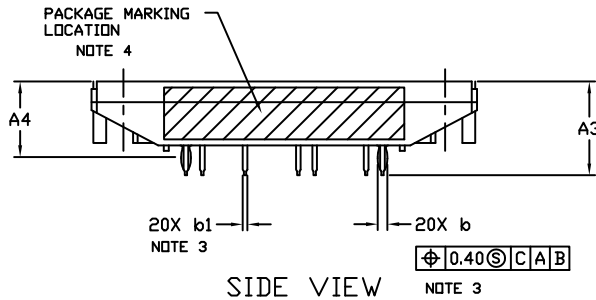


PIM20, 55x32.5 / Q0PACK  
CASE 180AA  
ISSUE C

DATE 08 NOV 2017

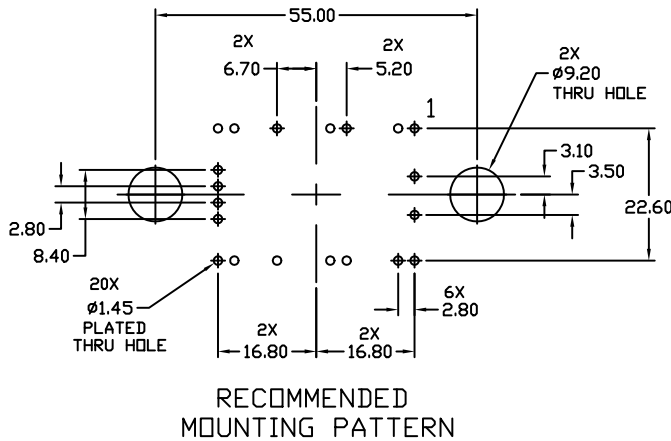


DIM	MILLIMETERS	
	MIN.	MAX.
A	11.33	12.33
A3	15.50	16.50
A4	12.88	BSC
b	1.61	1.71
b1	0.75	0.85
D	54.80	55.20
D1	65.70	70.10
D2	16.80	BSC
D3	6.70	BSC
D4	5.20	BSC
D5	2.80	BSC
E	32.30	32.70
E1	11.30	BSC
E2	4.20	BSC
E3	1.40	BSC
E4	3.50	BSC
E5	3.10	BSC
P	4.10	4.50
P1	8.50	9.50

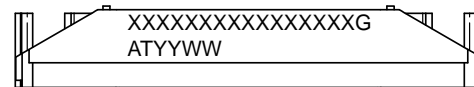


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A4.
4. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.



GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code  
G = Pb-Free Package  
AT = Assembly & Test Site Code  
YYWW = Year and Work Week Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	PIM20 55X32.5 / Q0PACK (PRESS FIT)	PAGE 1 OF 2



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY D. BUSHONG.	30 APR 2015
A	MODIFIED TOP AND SIDE VIEWS AND CHANGED MARKING DIAGRAM. REQ. BY A. LAI.	01 MAR 2016
B	CHANGED DIMENSION TABLE CALLOUTS FROM MIN & NOM TO MIN & MAX. REQ. BY F. ESTRADA.	01 FEB 2017
C	UPDATED MARKING DIAGRAM CODE INFORMATION. REQ. BY A. LAI.	08 NOV 2017

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